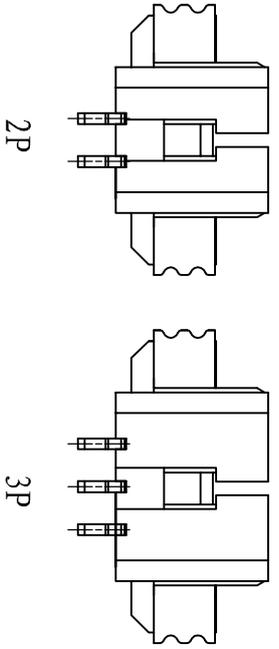
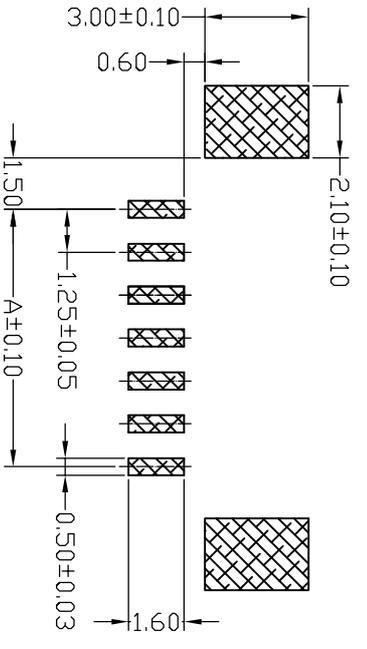
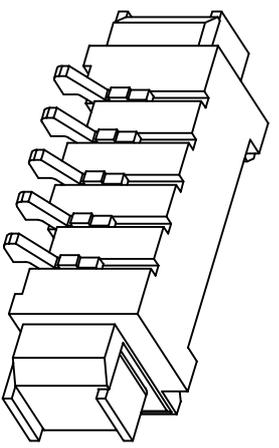
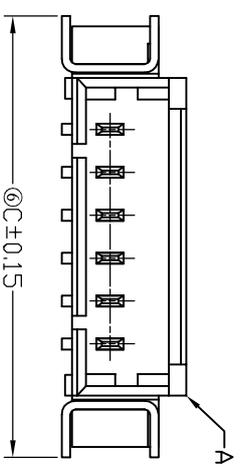
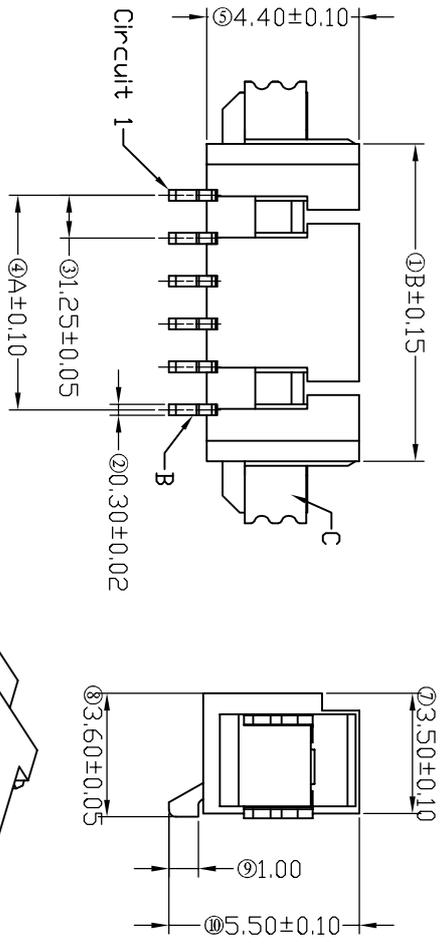


REV.	ECN. NO.	DESCRIPTION	APPD.
	NEW RELEASE		

SPECIFICATION

- 1 Contact resistance: $\leq 20m\Omega$
- 2 Insulation resistance: $\geq 100M\Omega$
- 3 Rated voltage: 125 V AC DC
- 4 Rated current: 1.0 A AC DC
- 5 Withstand Voltage: 250V AC/minute
- 6 Temperature Range: $-25^{\circ}C \sim +85^{\circ}C$



Circuit	Dimensions (mm)			Circuit	Dimensions (mm)		
	A	B	C		A	B	C
02	1.25	4.25	7.75	10	11.25	14.25	17.75
03	2.50	5.50	9.00	11	12.50	15.50	19.00
04	3.75	6.75	10.25	12	13.75	16.75	20.25
05	5.00	8.00	11.50	13	15.00	18.00	21.50
06	6.25	9.25	12.75	14	16.25	19.25	22.75
07	7.50	10.50	14.00	15	17.50	20.50	24.00
08	8.75	11.75	15.25	16	18.75	21.75	25.25
09	10.00	13.00	16.50				

SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

C	Solder Tab	2	Phosphor Bronze	Tin-plated
B	Contacts	2~16	Phosphor Bronze	Tin-plated
A	Insulator	1	LCP (UL94V-0)	Beige
NO.	DESCRIPTION	QTY	MATERIAL	PLATING/COLOR
		2		

Tolerance X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 Angle ±3.0°	Model Name: 1.25mmPITCH 90° WAFER SMT TYPEP	Model No: 1.25-3P贴片	SCALE: FULL	REVISION: B/0	UNIT: mm
	Drawn:	Checked:	Approved:	Date:	FILE
					DWG. NO.

深圳市首韩科技有限公司